

REMARKS

Claims 19-22 and 24-30 will be pending upon entry of the present amendment. Claims 1-18 and 23 are being canceled. Claims 19-22 are being amended. Claims 24-30 are being newly presented.

The applicant hereby affirms the election of claims 12-23. Accordingly, claims 1-11 are being canceled.

The drawings were objected to as failing to show the “dyke or barrier” of claims 22-23. Being filed herewith is a request for drawing change showing a dyke or barrier 52 in Figures 2A, 2B in accordance with claim 22 and the original specification. Claim 23 is being canceled.

Claims 19 and 21 were rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,379,988 to Peterson et al. (“Peterson”).

Peterson does not disclose the invention recited in claims 19 and 21, as amended. Amended claim 19 recites a packaged electronic device, ready for use, that includes a plastic protective package surrounding and supporting an electronic circuit, and a projecting portion of elastic material projecting from a surface of the electronic device into a window of the protective package to enable the electronic device to be activated through the projecting portion when the electronic device is in use. Peterson does not disclose an elastic projecting portion that extends from an electronic circuit and is structured to enable the electronic device to be activated through the projecting portion when the electronic device is in use. Instead, Peterson employs a window 36 attached to the outside of the package 14. Such a window 36 does not extend from a surface of an electronic circuit and does not extend into a window of a protective package. Moreover, Peterson does not disclose forming the window 36 from an elastic material.

Peterson also discloses a sacrificial protective layer 26, but that layer also does not satisfy the claimed limitations of the projecting portion. As implied by the “sacrificial” label, layer 26 is removed from a micro-electromechanical system (MEMS) device 24 in order for the MEMS device to operate (see Fig. 2C, col. 9). As a result, the sacrificial layer 26 is not structured to enable the electronic device to be activated through the projecting portion when the

electronic device is in use. Quite simply, the MEMS device 24 cannot operate with the sacrificial layer 26 in place.

For the foregoing reasons, claims 19 and 21 are not anticipated by Peterson.

Claim 20 was rejected under 35 U.S.C. § 103 as being unpatentable over Peterson in view of U.S. Patent No. 5,897,338 to Kaldenberg.

Peterson and Kaldenberg do not teach or suggest the invention recited in claim 20, as amended. In particular, Peterson and Kaldenberg do not teach or suggest the elastic projecting portion recited in claim 19, from which claim 20 depends. Peterson does not suggest altering the window 36 to make it elastic or to extend it from the MEMS device 24 or into the window of the plastic package 14. In addition, as discussed above, the MEMS device 24 cannot operate with the sacrificial layer 26 in place, so there is no suggestion of structuring the sacrificial layer to enable the MEMS device to be activated through the sacrificial layer.

Like Peterson, Kaldenberg employs a window 26 that is not elastic and does not extend from an electronic circuit. Kaldenberg also employs a deformable material 23 during formation of the device, but, like the sacrificial layer 26 of Peterson, that deformable material 23 is removed (see Fig. 3 and col. 3) prior to completion of the device. As a result, Kaldenberg does not suggest employing an elastic projecting portion that is structured to enable the electronic device to be activated through the projecting portion when the electronic device is in use.

For the foregoing reasons, claim 20 is non-obvious in view of Peterson and Kaldenberg.

Claim 22 was rejected under 35 U.S.C. § 103 as being unpatentable over Peterson in view of U.S. Patent No. 5,852,320 to Ichihashi. Like the other prior art, Ichihashi does not teach or suggest the elastic projecting portion recited in claim 19, from which claim 22 depends. Accordingly, claim 22 is non-obvious in view of Peterson and Ichihashi.

New claim 24 depends on claim 19, and thus, is allowable for the reasons discussed above.

Although the language of new claims 25-30 differs from that of claims 19-22 and 24, the allowability of claims 25-30 will be apparent in view of the above discussion.

The Commissioner is authorized to charge any additional fees due by way of this Amendment, or credit any overpayment, to our Deposit Account No. 19-1090.

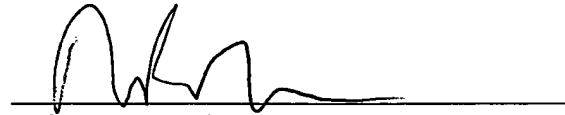
Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "**Version With Markings to Show Changes Made.**"

All of the claims remaining in the application are now clearly allowable. Favorable consideration and a Notice of Allowance are earnestly solicited.

Respectfully submitted,

Giovanni Frezza

SEED Intellectual Property Law Group PLLC

A handwritten signature in black ink, appearing to read 'Robert Iannucci', is written over a horizontal line.

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification:

The paragraph beginning at page 4, line 14 is being amended as follows:

Advantageously, a ring 52 is provided on the cap of the sensor 30, which is formed out of semiconductor material, for example. This ring (~~not shown~~)52 is filled with the covering layer 50 material. Thus, the ring 52 will form a barrier or containing dyke for the covering layer 50.

The paragraph beginning at page 6, line 3 is being amended as follows:

In this embodiment it is only necessary that ~~the~~ projecting portion 51 abuts against the lug 13, so that the formation of the projecting portion 51 is less critical.

The paragraph beginning at page 7, line 19 is being amended as follows:

In this embodiment, the covering ~~layer~~ 50 is transparent to UV radiation.

In the Claims:

Claims 1-18 and 23 are being canceled.

Claims 19-22 are being amended as follows:

19. (Amended) A plastic protective package for packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit; ~~comprising~~

a support for an electronic device a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over a portion of the electronic device such that the electronic device can be at least partially activated from the outside of said protective package; and wherein said protective package is provided with a hole or a window aligned to at least one portion of said integrated device that is at least partially filled by

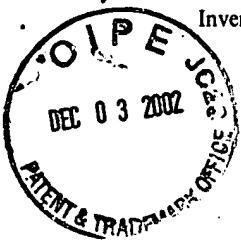
a projecting portion of elastic material projecting from a surface of the electronic device into the window, the projecting portion being structured to enable the electronic device to be activated through the projecting portion when the electronic device is in use.

20. (Amended) The packaged electronic device ~~plastic protective package~~ according to claim 19 wherein said projecting portion is shaped to form a ring on the ~~integrate device~~ electronic circuit.

21. (Amended) The packaged electronic device ~~plastic protective package~~ according to claim 19 wherein said ~~hole~~ window has tapering walls toward said electronic circuit.

22. (Amended) The packaged electronic device ~~plastic protective package~~ according to claim 19 wherein said projecting portion is surrounded by dyke or barrier formed on ~~the a~~ a surface of the electronic ~~device~~ circuit.

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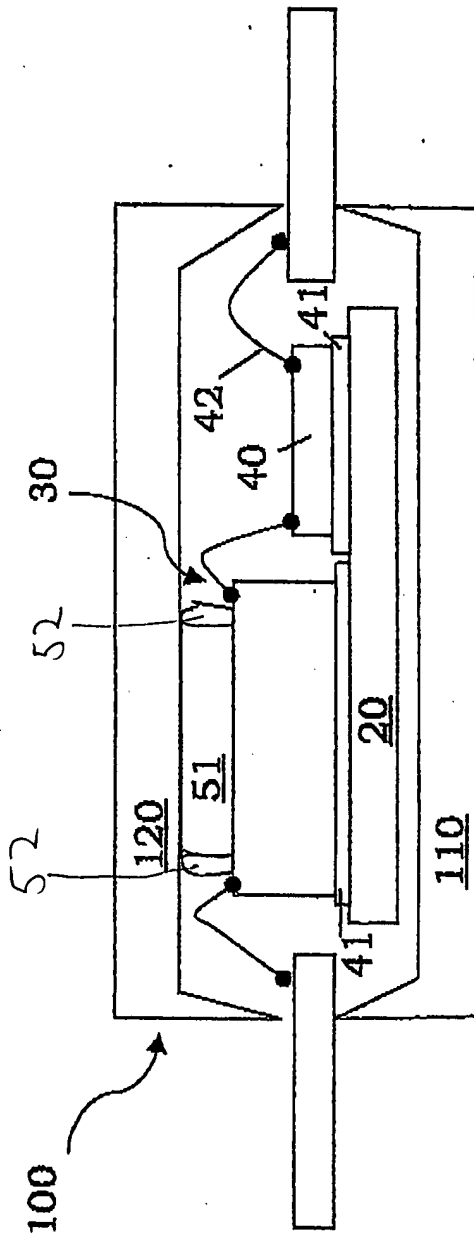


FIG. 2A

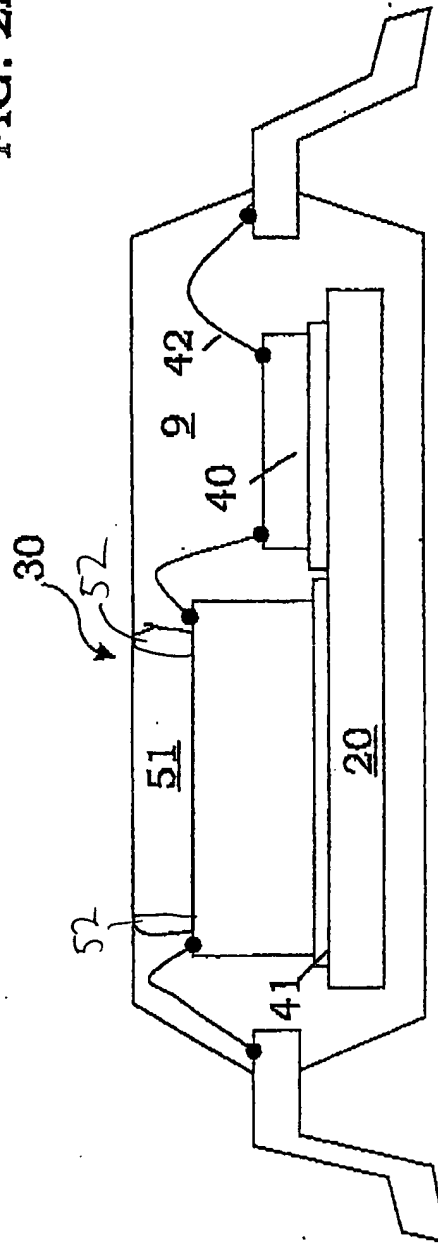


FIG. 2B